19-3705; Rev 0; 5/05





## **Dual, Low-Voltage Linear Regulator Controllers** with External MOSFETs

#### **General Description**

The MAX8737 dual high-power linear regulator controllers use external n-channel MOSFETs to generate two independent low-voltage supplies for notebook computers. The MAX8737 delivers low output voltages from 0.5V to 2.5V (±5mV no-load accuracy). The external components allow scalable current design with loads up to 5A with excellent load regulation (1%). The regulator operates from a low input voltage, which also reduces the power dissipation in the external n-channel MOSFET. The controller powers the external MOSFET gate driver from the standard 5V system supply.

The MAX8737 includes current and thermal limits to prevent damage to the linear regulator. The MAX8737 uses an external resistive divider to fold back the current limit, reducing the overall power dissipation. The MAX8737 uses an external resistive-divider in series with the current-sense input (CS\_), providing foldback current-limit protection, and effectively reducing the short-circuit power dissipation.

An output undervoltage timeout is available for low-cost applications that omit the current-sense resistor. The output undervoltage (UVP) timing depends on the magnitude of the voltage at Vour. The UVP detects and shuts down the LDO if the output voltage drops out of regulation. The controller uses an adjustable reference input (REFIN\_) to set the nominal output voltage (VOUT), which minimizes the cost and makes the stability independent of the output voltage.

Each linear regulator features an adjustable soft-start function, and generates a delayed power-good (PGOOD) signal that signals when the linear regulator is in regulation. The MAX8737 is a low-cost solution requiring few external components and is available in a small, 4mm x 4mm, 16-pin thin QFN package.

### **Applications**

Notebook and Desktop Computers Point-of-Load Regulators VMCH and VCCP CPU Supplies Low-Voltage Bias Supplies Servers

#### **Features**

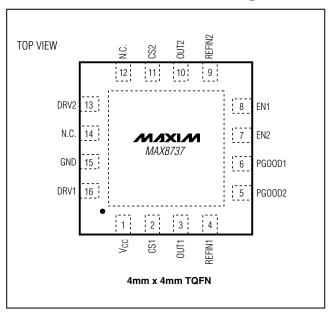
- **♦ Low-Cost Dual Linear Regulators**
- ♦ Output Voltage Accuracy ±5mV
- ♦ Independent 0.5V to 2.5V Reference Inputs
- **♦** Foldback Current-Limit Protection
- ♦ Output Undervoltage-Lockout Protection
- ◆ Thermal Limit (Internal Sensor)
- ♦ 1.0V to 5.5V Input Supply Voltage (External FET Drain)
- ♦ 5V Bias Supply Voltage
- **♦** Independent Power-Good Open-Drain Outputs
- ♦ Independent Enable Inputs
- **♦** Soft-Shutdown Output Discharge
- **♦ Low Supply Current (0.5mA)**
- ♦ 5µA (max) Shutdown Supply Current

#### **Ordering Information**

PART	TEMP RANGE PIN-PACKAGE
MAX8737ETE	-40°C to +85°C 16 Thin QFN-EP* 4mm x 4mm
MAX8737ETE+	-40°C to +85°C 16 Thin QFN-EP* 4mm x 4mm

<sup>\*</sup>EP = Exposed pad.

### **Pin Configuration**



MIXIM

Maxim Integrated Products 1

<sup>+</sup>Denotes lead-free packaging.

#### **ABSOLUTE MAXIMUM RATINGS**

V <sub>CC</sub> to GND	Operating Temperature Range  MAX8737ETE  Junction Temperature  Storage Temperature Range  Lead Temperature (soldering, 10s)  -40°C to +85°C  +150°C  +150°C  +300°C
above +70°C)	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 5V, EN_{-} = CS_{-} = V_{CC}, V_{REFIN} = 1.0V, T_A = 0^{\circ}C$  to +85°C, unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	SYMBOL	CON	DITIONS	MIN	TYP	MAX	UNITS
Supply Voltage Range	Vcc			4.75		5.50	V
V <sub>CC</sub> Undervoltage Lockout Threshold		Rising edge, 200mV	' hysteresis (typ)	4.1	4.35	4.6	V
V <sub>CC</sub> Quiescent Supply Current	Icc	EN1 = EN2 = V <sub>CC</sub>			0.5	1	mA
V <sub>CC</sub> Shutdown Supply Current		EN1 = EN2 = GND			0.1	5	μΑ
REFIN to OUT Offset Voltage	Vout_			-5		+5	mV
OUT_ Input Bias Current	I <sub>OUT</sub> _			-1		+1	μΑ
DRIVERS							
DRV_ Output Voltage Swing		Output high; V <sub>OUT</sub> _ I <sub>LOAD</sub> = 1mA	= V <sub>REFIN</sub> 25mV,	V <sub>CC</sub> - 0.3	V <sub>CC</sub> - 0.05		V
(Note 1)		Output low; V <sub>OUT</sub> = I <sub>LOAD</sub> = 1mA	= VREFIN_ + 25mV,		0.03	0.3	V
DRV_ Maximum Sourcing Current		Vout_ = Vrefin 2	25mV; V <sub>DRV</sub> = 3V	6	14		mA
DRV_ Maximum Sinking Current		Vout_ = Vrefin_ +	25mV; V <sub>DRV</sub> = 3V	6	14		mA
OUT_ to DRV_ Transconductance (Large Signal)	G <sub>MDRV</sub>				0.8		S
DRV_ Power-Supply Rejection Ratio		10Hz < f < 10kHz, l <sub>[</sub> 10nF	DRV = 1mA, CDRV =		-80		dB
DRV_ Soft-Start Charging Current	ISOFT			40	170	400	μΑ
REFERENCE INPUT							
REFIN_ Voltage Range	V <sub>REFIN</sub> _	$V_{CC} = 4.75V \text{ to } 5.5V$	1	0.5		2.5	V
REFIN_ Input Bias Current	I <sub>REFIN</sub> _	V <sub>REFIN</sub> _ = 0 to 2.5V		-100	-10	+100	nA
FAULT PROTECTION							
Thermal Shutdown Threshold	T <sub>SHDN</sub>	Hysteresis = 20°C			+125		°C
Current-Limit Threshold	VILIM	Vcs Vout_	$T_A = 0$ °C to +85°C	7	10	13	mV
Current-Limit mileshold	V ILIIVI	VCS VOUI_	$T_A = +85^{\circ}C$	7.5	10	12.5	1117
CS_ Input Current				-1		+1	μΑ
Linear Regulator UVP Threshold (Slow)	UVP(SLOW)	With respect to V <sub>REI</sub>	FIN; CS_ = V <sub>CC</sub>	72	80	88	%

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 5V, EN_{-} = CS_{-} = V_{CC}, V_{REFIN} = 1.0V, T_A = 0^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted. Typical values are at } T_A = +25^{\circ}C.)$ 

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Linear Regulator UVP Threshold (Fast)	UVP(FAST)	With respect to V <sub>REFIN</sub> ; CS_ = V <sub>CC</sub>	54	60	66	%
Slow Short-Circuit Timer Duration	tuvp(slow)	With respect to V <sub>REFIN</sub> ; CS <sub>_</sub> = V <sub>CC</sub>		75		μs
Fast Short-Circuit Timer Duration	tuvp(fast)	With respect to V <sub>REFIN</sub> ; CS <sub>_</sub> = V <sub>CC</sub>		5		μs
Discharge-Mode On-Resistance OUT_ Pin	Rout			10		Ω
INPUTS AND OUTPUTS						
EN_ Input Low Level					0.6	V
EN_ Input High Level		Rising edge, 200mV (typ) hysteresis	1.6			V
Enable Leakage Current			-1		+1	μΑ
Power-Good Trip Threshold (Lower)		With respect to error comparator threshold, hysteresis = 4% (falling edge)	-15	-12	-9	%
Power-Good Startup Delay				2		ms
Power-Good Propagation Delay	tpgood	OUT_ forced 2% beyond PGOOD_ trip threshold		1		μs
Power-Good Output Low Voltage		ISINK = 4mA			0.3	V
		V <sub>OUT</sub> = 1.0V (PGOOD_ high impedance),				

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{CC} = 5V, EN_{-} = CS_{-} = V_{CC}, V_{REFIN} = 1.0V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted.})$  (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
Supply Voltage Range	Vcc		4.75		5.50	V
V <sub>CC</sub> Undervoltage Lockout Threshold		Rising edge 200mV hysteresis (typ)	4.1		4.6	V
V <sub>CC</sub> Quiescent Supply Current	Icc	EN1 = EN2 = V <sub>CC</sub>			1.5	mA
V <sub>CC</sub> Shutdown Supply Current		EN1 = EN2 = GND			5	μΑ
REFIN to OUT Offset Voltage	V <sub>OUT</sub> _		-7		+7	mV
DRIVERS						
DRV_ Output Voltage Swing		Output high; V <sub>OUT</sub> = V <sub>REFIN</sub> - 25mV; I <sub>LOAD</sub> = 1mA	V <sub>CC</sub> - 0.3			V
(Note 1)		Output low; V <sub>OUT</sub> = V <sub>REFIN</sub> + 25mV: I <sub>LOAD</sub> = 1mA			0.3	V
DRV_ Maximum Sourcing Current		V <sub>OUT</sub> = V <sub>REFIN</sub> - 25mV; V <sub>DRV</sub> = 3V	3.5			mA
DRV_ Maximum Sinking Current		V <sub>OUT</sub> = V <sub>REFIN</sub> + 25mV; V <sub>DRV</sub> = 3V	3.5			mA
DRV_ Soft-Start Charging Current	ISOFT		40		400	μΑ

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 5V, EN_{-} = CS_{-} = V_{CC}, V_{REFIN} = 1.0V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C, \text{ unless otherwise noted.})$  (Note 2)

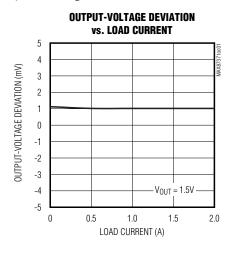
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
REFERENCE INPUT						
REFIN_ Voltage Range	V <sub>REFIN</sub> _	V <sub>CC</sub> = 4.75V to 5.5V	0.5		2.5	V
FAULT PROTECTION						
Current-Limit Threshold	VILIM	V <sub>CS</sub> V <sub>OUT</sub> _	6.5		13.5	mV
Linear Regulator UVP Threshold (Slow)	UVP(SLOW)	With respect to V <sub>REFIN</sub> ; CS_ = V <sub>CC</sub>	72		88	%
Linear Regulator UVP Threshold (Fast)	UVP(FAST)	With respect to V <sub>REFIN</sub> ; CS_ = V <sub>CC</sub>	54		66	%
INPUTS AND OUTPUTS	•					
EN_ Input Low Level					0.6	V
EN_ Input High Level			1.6			V
Power-Good Trip Threshold (Lower)		With respect to error comparator threshold, hysteresis = 4% (falling edge)	-15		-9	%
Power-Good Output Low Voltage		I <sub>SINK</sub> = 4mA			0.3	V

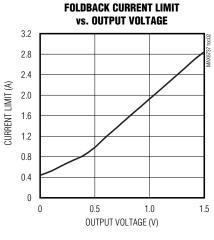
Note 1: Low threshold n-channel MOSFET is required for 2.5V (±2%) output.

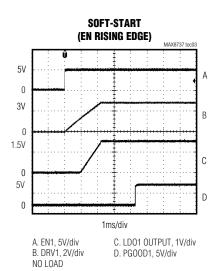
Note 2: Specifications to -40°C are guaranteed by design, not production tested.

### Typical Operating Characteristics

(Circuit of Figure 1,  $T_A = +25$ °C, unless otherwise noted.)

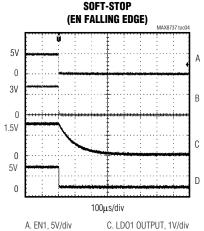


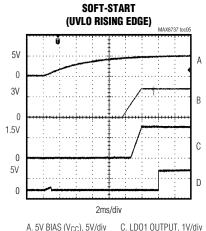


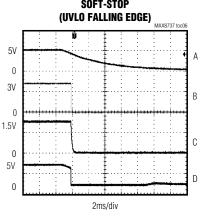


### **Typical Operating Characteristics (continued)**

(Circuit of Figure 1, T<sub>A</sub> = +25°C, unless otherwise noted.)



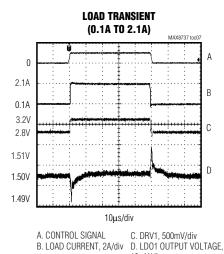


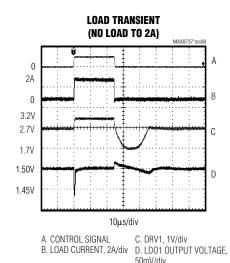


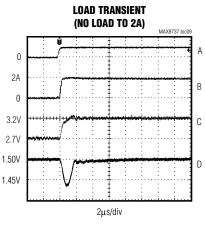
B. DRV1, 2V/div D. PG00D1, 5V/div NO LOAD

A. 5V BIAS (V<sub>CC</sub>), 5V/div B. DRV1, 2V/div D. PG00D1, 5V/div NO LOAD, EN = V<sub>CC</sub>

A. 5V BIAS (V<sub>CC</sub>), 5V/div C. LDO1 OUTPUT, 1V/div B. DRV1, 2V/div D. PG00D1, 5V/div NO LOAD, EN = V<sub>CC</sub>





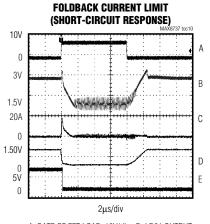


A. CONTROL SIGNAL

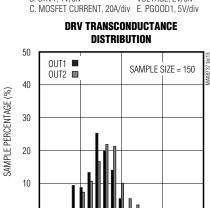
C. DRV1, 1V/div B. LOAD CURRENT, 2A/div D. LDO1 OUTPUT VOLTAGE,

### Typical Operating Characteristics (continued)

(Circuit of Figure 1,  $T_A = +25$ °C, unless otherwise noted.)



A. GATE OF FET LOAD, 10V/div D. LD01 0UTPUT B. DRV1, 1V/div VOLTAGE, 2V/div C. MOSFET CURRENT, 20A/div E. PG00D1, 5V/div



1.0

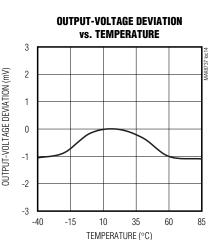
TRANSCONDUCTANCE (S)

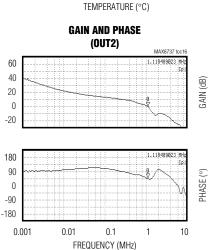
1.3

1.5

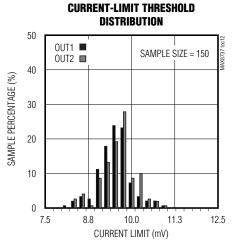
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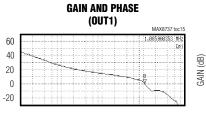
OUTPUT OFFSET VOLTAGE (mV)

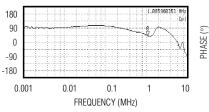




1.05V OUTPUT, 2A LOAD,  $C_{OUT} = (1) 22\mu F$  1206 6V CERAMIC







1.5V OUTPUT, 1A LOAD,  $C_{OUT}$  = (1)  $10\mu F$  1206 16V CERAMIC

0.5

0.8

### \_Pin Description

PIN	NAME	FUNCTION
1	Vcc	Analog and Driver Supply Input. Connect to the system supply voltage (+5.0V). Bypass V <sub>CC</sub> to analog ground with a 1µF or greater ceramic capacitor.
2	CS1	Positive Current-Sense Input for LDO1. To enable (foldback) current limit, connect CS1 to the positive terminal of the current-sense element as shown in Figure 1. The MAX8737 driver reduces the gate voltage when the 10mV (typ) current-limit threshold is exceeded. When CS1 is connected to V <sub>CC</sub> , the MAX8737 disables the current-limit protection and enables the output undervoltage protection (see the UVP Short-Circuit Protection section).
3	OUT1	Output Feedback-Sense, Negative Current-Sense, and Discharge Input for LDO1. Connect directly to the linear regulator output. When LDO1 is disabled, OUT1 is discharged through an internal $10\Omega$ FET to GND.
4	REFIN1	External Reference Input for LDO1. REFIN1 sets the main output regulation voltage (V <sub>OUT1</sub> = V <sub>REFIN1</sub> ).
5	PGOOD2	Open-Drain Power-Good Output for LDO2. PGOOD2 is low when the output voltage is more than 12% (typ) below the normal regulation point, during soft-start, and in shutdown. Approximately 2ms (typ) after OUT2 reaches the regulation voltage (REFIN2), PGOOD2 becomes high impedance as long as the output remains in regulation.
6	PGOOD1	Open-Drain Power-Good Output for LDO1. PGOOD1 is low when the output voltage is more than 12% (typ) below the normal regulation point, during soft-start, and in shutdown. Approximately 2ms (typ) after OUT1 reaches the regulation voltage (REFIN1), PGOOD1 becomes high impedance as long as the output remains in regulation.
7	EN2	Enable Input for LDO2. Connect EN2 to Vcc for always ON. When EN2 is pulled low, the linear regulator shuts down and pulls the output to ground.
8	EN1	Enable Input for LDO1. Connect EN1 to Vcc for always ON. When EN1 is pulled low, the linear regulator shuts down and pulls the output to ground.
9	REFIN2	External Reference Input for the Secondary Regulator (LDO2). REFIN2 sets the main output regulation voltage (Vout2 = VREFIN2).
10	OUT2	Output Sense, Negative Current-Sense Input, and Discharge Input for the Secondary Regulator (LDO2). Connect directly to the linear regulator output. When the LDO2 is disabled, OUT2 is discharged through an internal $10\Omega$ FET to GND.
11	CS2	Positive Current-Sense Input for LDO2. To enable (foldback) current limit, connect CS2 to the positive terminal of the current-sense element as shown in Figure 1. The MAX8737 driver reduces the gate voltage when the 10mV (typ) current-limit threshold is exceeded. When CS2 is connected to V <sub>CC</sub> , the MAX8737 disables the current-limit protection and enables the output undervoltage protection (see the UVP Short-Circuit Protection section).
12, 14	N.C.	Not Internally Connected
13	DRV2	External N-Channel Gate Drive for LDO2
15	GND	Ground. Connect the thin QFN backside pad to GND.
16	DRV1	External N-Channel Gate Drive for LDO1
	EP	Exposed Pad. Connect the thin QFN backside pad to GND.

#### Detailed Description

The MAX8737 is a dual, low-dropout, external n-channel linear regulator controller for low-voltage notebook computer power supplies. The linear regulator provides a 0.5V to 2.5V (±5mV no-load) output for powering the low-voltage supplies to desktop and notebook CPU chipsets (VCCP and VCC\_MCH). The regulator operates from low input voltage, which also reduces the power dissipation in the external n-channel MOSFET. The controller powers the external MOSFET gate driver from the standard 5V system supply.

The controller features independent enable inputs (EN ), PGOOD outputs (PGOOD ), input undervoltage lockout (UVLO), and output undervoltage protection (UVP). The controller uses an adjustable reference input (REFIN\_) to set the nominal output voltage (VOUT), which minimizes the cost and makes the stability independent of the output voltage. An output UVP timing depends on the magnitude of the voltage at VOUT. The UVP detects and shuts down the LDO if the output voltage drops below the nominal output voltage (VREFIN). Each linear regulator features an adjustable soft-start function, and generates a delayed PGOOD signal that signals when the linear regulator is in regulation. The MAX8737 uses an external resistor-divider in series with the current-sense input (CS\_), providing foldback current-limit protection, and effectively reducing the short-circuit power dissipation. The MAX8737 is available in a thin QFN package to reduce the thermal impedance, and improve the thermal coupling between the controller and the external MOSFETs.

#### **REFIN** Input

The low-cost linear regulator uses an adjustable reference input (REFIN\_) to set the nominal output voltage, which minimizes cost and simplifies the stability—the stability calculation is independent of V<sub>OUT</sub>. The output voltage accuracy depends on the accuracy of the source generating the REFIN voltage. Multiple accurate references are typically available elsewhere in the system (such as the switching regulator providing the low-voltage input supply). If lower output accuracy is acceptable, divide down and filter another regulated output voltage supply.

To set output voltage, select R2 =  $100k\Omega$  and select R1 using the following formula:

$$R1 = \left(\frac{V_{REF}}{V_{REFIN}} - 1\right)R2$$

#### **Soft-Start**

When the LDO is activated, the respective DRV\_ is pulled up from GND with a typical soft-start current of 170 $\mu$ A. The soft-start current limits the output voltage slew rate and also limits the initial current spike through the external n-channel MOSFET. The slew rate is also limited by the compensation capacitance used at the DRV\_ pin.

The maximum drain current during startup is the ratio of COUT to CCOMP, multiplied by the soft-start current ISOFT of 170µA (typ).

#### **Enable and Power Good**

The MAX8737 has independent enable control inputs (EN1, EN2). Drive EN1 high to enable output 1. Drive EN2 high to enable output 2. When EN\_ is driven low, the corresponding DRV\_ and PGOOD\_ pins are pulled to GND, and the output is discharged through a  $10\Omega$  switch

There are two independent PGOOD\_ outputs indicating the supply status. PGOOD\_ is pulled high 2ms after the controller is enabled (EN\_ is pulled high and VCC exceeds its UVLO threshold), and the output is in regulation. If either output is out of regulation, the respective PGOOD\_ goes low immediately. The MAX8737 pulls PGOOD\_ low if the output voltage drops below the lower trip threshold of -12% (typ) or when VCC is in UVLO or when EN\_ is pulled low.

#### Soft-Stop

The MAX8737 enables a soft-stop function that discharges the output through an internal  $10\Omega$  switch when EN\_ is driven low or VCC is in UVLO. The discharge time of the output depends on the output capacitance, output load, and the exact resistance of the internal discharge switch. To slow down the discharge rate, add resistance in series with the OUT\_ pin.

#### 5.0V Bias Supply (Vcc)

The linear regulator operates with very low input voltages.  $V_{IN}$  may be as low as 1.2V, so a secondary 5V supply is required to provide sufficient bias to the gate drivers. Locally decouple the  $V_{CC}$  input with  $1\mu F$  or greater of ceramic capacitance.

#### **Current Limit**

The MAX8737 features a current limit that monitors the voltage across the current-sense resistor, which limits VCS\_ - VOUT\_ to 10mV (typ). However, in case of a short-circuit condition, the power dissipation across the external FET will be extremely high. To protect the external FET, the MAX8737 uses an external resistive divider (see Figure 1) to fold back the current limit, reducing the overall power dissipation. The foldback

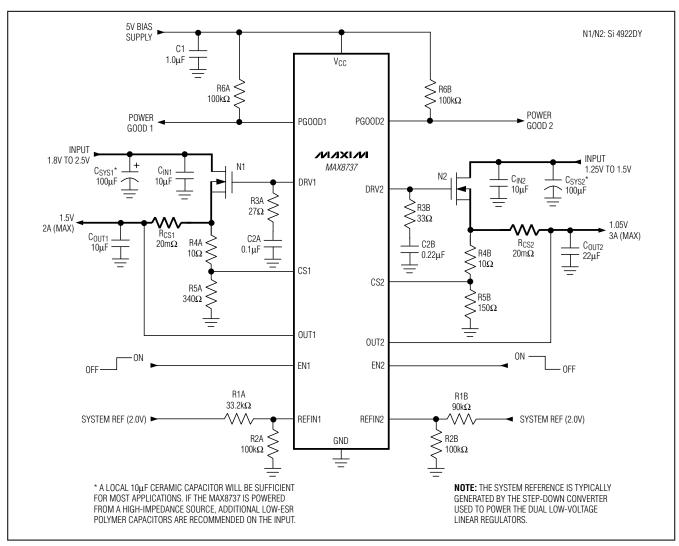


Figure 1. Typical Operating Circuit with Current Limit

resistor network is calculated using the short-circuit current (ISHORT), the maximum load current (IMAX), current-sense resistor (RCS), the 10mV ( $\pm$ 3mV) current-limit threshold (VILIM), and the external reference input (REFIN\_). See Figure 3:

 Pick the Rcs requirement for maximum short-circuit current:

2) Select R1 =  $10\Omega$  and select R2 using the following formula:

$$R2 = \frac{(V_{REFIN} + V_{ILIM})R1}{I_{MAX}R_{CS} - V_{ILIM}}$$

#### **UVP Short-Circuit Protection**

There are two levels of short-circuit UVP available in the controller. When the current-limit protection is not used (CS\_= VCC), the output undervoltage timeout protection is enabled, which protects the regulator against short circuits. Output UVP timing depends on the magnitude of the output voltage drop. To clear the UVP fault latch, toggle the respective EN\_ input, or cycle VCC below its UVLO threshold.

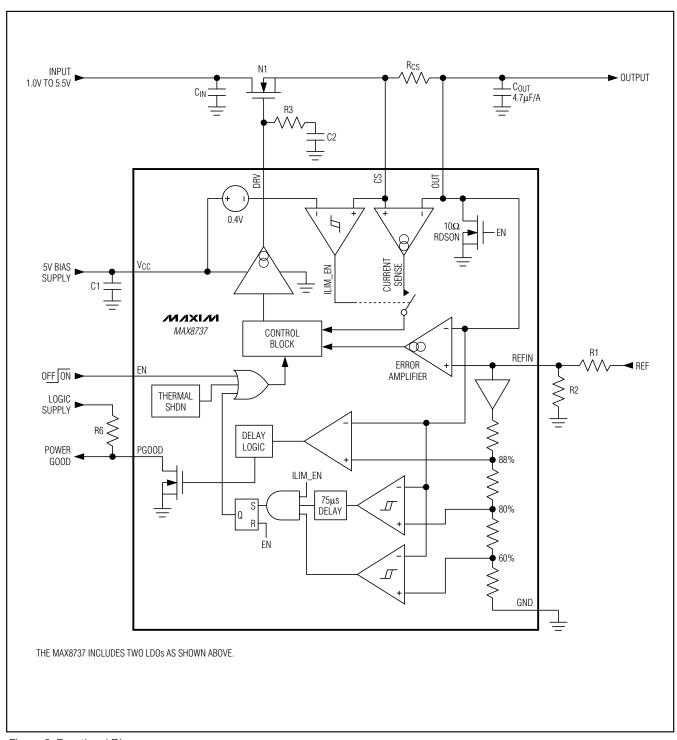


Figure 2. Functional Diagram

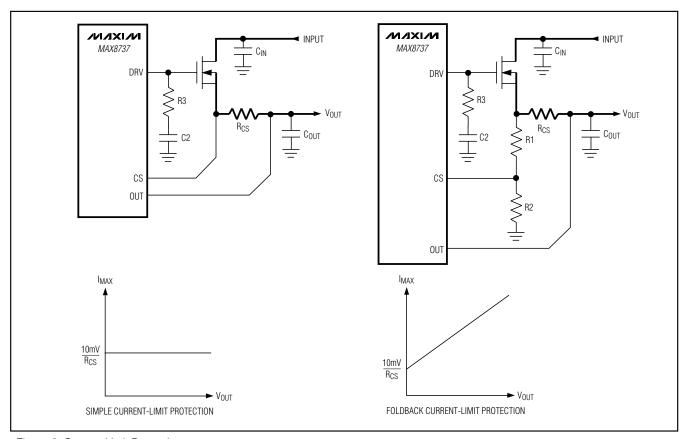


Figure 3. Current-Limit Protection

#### Slow UVP

If the output drops below 80% of the nominal output voltage (VREFIN) for 75 $\mu$ s, the MAX8737 shuts down the LDO and pulls the DRV\_ pin to ground. If the output voltage returns above 80% of the nominal output voltage (VREFIN) within the 75 $\mu$ s, the controller ignores the load transient.

#### Fast UVP

If the output voltage drops below 60% of the nominal output voltage (VREFIN) for approximately 5 $\mu$ s, the MAX8737 immediately shuts down and pulls the DRV\_pin to ground. If the output voltage returns above 80% of the nominal output voltage (VREFIN) within the 5 $\mu$ s, the controller ignores the load transient.

#### **Thermal Protection**

The MAX8737 is available in a thin QFN package to reduce the thermal impedance, and improve the thermal coupling between the controller and the external MOSFETs. When the controller's junction temperature exceeds  $T_J = +125^{\circ}C$  (max), a thermal sensor turns off

the external pass transistor, allowing the system to cool. The thermal sensor turns the pass transistor back on once the controller's junction temperature drops by approximately 20°C.

#### Design Procedure

#### Input Capacitor Selection (CIN)

Typically, the MAX8737 is powered from the output of a step-down regulator, effectively providing a low-impedance source. A local 10µF ceramic capacitor at  $V_{IN}$  and a 1.0µF ceramic capacitor at  $V_{BIAS}$  should be sufficient for most applications. If the linear regulator is connected to a high-impedance input, low-ESR polymer capacitors are recommended on the input.

#### Output Capacitor Selection (COUT)

To maintain stability and provide good transient response, the MAX8737 requires  $4.7\mu\text{F/A}$  ( $4.7\mu\text{F}$  minimum) of low ESR ceramic capacitor at the output. The regulator remains stable with capacitances higher than the minimum. When selecting the output capacitor to

provide good transient response, the capacitor's ESR should be minimized:

$$\Delta V_{OUT} = \Delta I_{OUT} \times ESR$$

where  $\Delta I_{OUT}$  is the maximum peak-to-peak load current step, and  $\Delta V_{OUT}$  is the transient output-voltage tolerance.

#### **Regulator Compensation**

The compensation network (R3\_, C2\_) is customizable and depends on load and MOSFET characteristics:

- Use of ceramic output capacitors with low RESR to ensure stability and minimize ESR voltage drop at load step
- Strength of the external n-channel MOSFET (g<sub>M</sub>), its forward transconductance (g<sub>FS</sub>), and the gate-tosource capacitance (C<sub>GS</sub>)
- The driver transconductance (GMDRV) of the integrated circuit driver
- Load current range (including the minimum load): IMIN to IMAX

#### Recommended Procedure

Use the CGS, gFS, ID from the chosen transistor data sheet and use the equation below to translate the measured gFS to gM for normal operation:

1) Determine the LDO transconductance using the MOSFET's forward transconductance (gFS), and the drain current (ID) used to test the selected MOSFET:

$$g_{M} = g_{FS} \sqrt{\frac{I_{MAX}}{I_{D}}}$$

 Calculate the compensation resistor based on the output capacitor (COUT), the MOSFET's gate-tosource capacitance (CGS = CISS - CRSS), and the minimum driver transconductance:

$$R3 = \sqrt{\frac{C_{OUT}}{C_{GS}g_{M} \times 0.5S}}$$

 Calculate the compensation capacitance using the minimum load current (I<sub>MIN</sub>) and compensation resistor value calculated above:

$$C2 = \frac{2V_TC_{OUT}}{I_{MIN}G_{MDRV}(R3)^2}$$

where  $V_T = 25 \text{mV}$ .

**Example:** The example below is used to demonstrate the stability calculation for the application circuit in Figure 1.

Choose V<sub>OUT</sub> = 1.05V and I<sub>MAX</sub> = 3A and the minimum load can be determined from the foldback current-limit resistance:

$$I_{MIN} = \frac{V_{OUT}}{R1 + R2} \approx 6mA$$

2) For the selected MOSFET (Si4922DY),  $C_{GS}$  = 2000pF at 1.5V, and  $g_{FS}$  = 30S at  $I_{D}$  = 8.8A:

$$g_M = 30S \sqrt{\frac{3A}{8.8A}} = 17.5S$$

- 3) The output capacitor must be at least 4.7μF/A. Therefore the design must use a minimum 14.1μF capacitor. The closest standard capacitor value is 22μF.
- 4) Based on the above operating conditions and component selection, the compensation resistor value should be:

$$R3 = \sqrt{\frac{22\mu F}{2nF \times 17.5S \times 0.5S}} = 35\Omega$$

5) Finally, select the compensation capacitor value:

$$C2 = \frac{2 \times 25 \text{mV} \times 22 \mu F}{6 \text{mA} \times 15 \times (35 \Omega)^2} = 0.15 \mu F$$

#### **External MOSFET Selection**

The MAX8737 uses an n-channel MOSFET as the series pass transistor instead of a p-channel MOSFET to reduce cost. The selected MOSFET must have a gate threshold voltage (at the required max load) that meets the following criteria:

$$V_{GS\_MAX} \le V_{CC} - V_{OUT}$$

where  $V_{CC}$  is the controller bias voltage, and  $V_{GS\_MAX}$  is the maximum gate voltage required to yield the onresistance ( $R_{DS\_ON}$ ) specified by the manufacturer's data sheet. Make sure that input-to-output voltage meets the condition below to avoid entering dropout, where output voltage starts to decrease and any ripple on the input also passes through to the output.  $R_{DSON}$  has a positive temperature coefficient (approximately

0.5%/°C); therefore, the value of R<sub>DSON</sub> at the highest operating junction temperature should be used:

$$V_{IN\_MIN} - V_{OUT\_MAX} \ge I_{MAX}(R_{DSON\_MAX} + R_{CS})$$

where  $V_{IN\_MIN}$  is the minimum input voltage at the drain of the MOSFET.

#### **MOSFET Power Dissipation**

The maximum power dissipation of the MAX8737 depends on the thermal resistance of the external n-channel MOSFET package, the board layout, the temperature difference between the die and ambient air, and the rate of airflow. The power dissipated in the MOSFET is:

The maximum allowable power dissipation is determined by the following formula:

$$R_{DIS(MAX)} = \frac{T_{J(MAX)} - T_{A}}{\theta_{JC} + \theta_{CA}}$$

where T<sub>J</sub>(MAX) is the maximum junction temperature (+150°C), T<sub>A</sub> is the ambient temperature, θ<sub>J</sub>C is the thermal resistance from the die junction to the package case, and θ<sub>CA</sub> is the thermal resistance from the case through the PC board, copper traces, and other materials to the surrounding air. Standard 8-pin SO MOSFETs are typically rated for 2W, while new power packages (PowerPAK<sup>TM</sup>, DirectFET<sup>TM</sup>, etc.) can achieve power dissipation ratings as high as 5W. For optimum power dissipation, use a large ground plane with good thermal contact to ground and use wide input and output traces. Extra copper on the PC board increases thermal mass and reduces the thermal resistance of the board. See Figure 4.

#### **PC Board Layout Guidelines**

Due to the high-current paths and tight output accuracy required by most applications, careful PC board layout is required. An evaluation kit (MAX8737EVKIT) is available to speed design. It is important to keep all traces as short as possible to minimize the highcurrent trace dimensions to reduce the effect of undesirable parasitic inductance. The MOSFET dissipates a fair amount of heat due to the high currents involved, especially during large input-to-output voltage differences. To dissipate the heat generated by the MOSFET, make power traces very wide with a large amount of copper area. An efficient way to achieve good power dissipation on a surface-mount package is to lay out copper areas directly under the MOSFET package on multiple layers and connect the areas through vias. Use a ground plane to minimize impedance and inductance.

In addition to the usual high-power considerations, here are four tips to ensure high output accuracy:

- Ensure that the feedback connection to C<sub>OUT</sub> is short and direct.
- Place the reference input resistors next to the REFIN\_pin.
- Place RC and CC next to the DRV\_pin.
- Ensure REFIN\_ and DRV\_ traces are away from noisy sources to ensure tight accuracy.

PowerPAK is a registered trademark of Vishay Siliconix. DirectFET is a trademark of International Rectifier Corp.

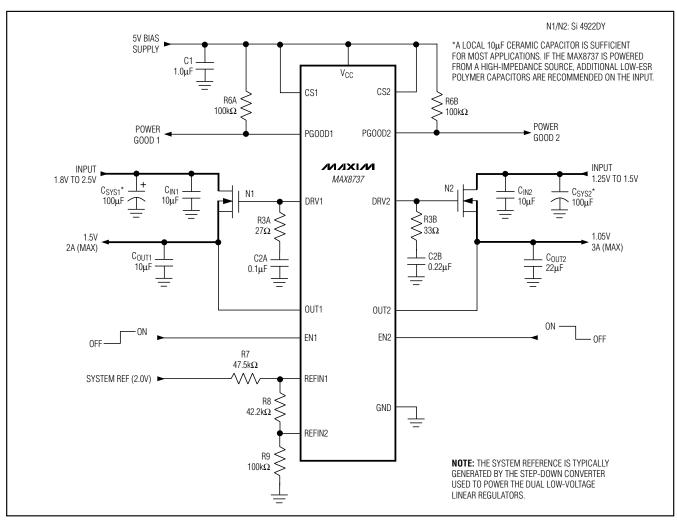


Figure 4. Typical Operating Circuit with Output Undervoltage Protection

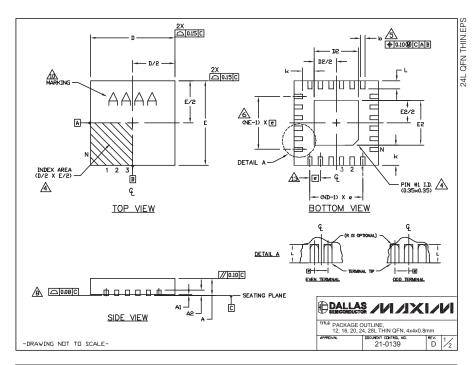
\_Chip Information

TRANSISTOR COUNT: 1562

PROCESS: BICMOS

#### Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



				COM	NDN	DIME	IIZN	ZNE									Ε	XPOS	ED	PAD	VAR	ITAI		
PKG	12	2L 4×	:4	16	L 4x	4	20	)L 4×	4	24	4L 4×	(4	25	BL 4×	4	DVC.			1)2			E5		DOWN
REF.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	PKG. CODE	2	MIN.	NOM.	MAX.	MIN.	NDM.	MAX.	ALLOWED
A	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	0.70	0.75	0.80	T124	4-2	1.95	2.10	2.25	1.95	2.10	2.25	ND
A1	0.0	0.02	0.05	0.0	20.0	0.05	0.0	0.02	0.05	0,0	0.02	0.05	0.0	0.02	0.05	T124	4-3	1.95	2.10	2.25	1.95	2.10	2.25	YES
A2		.20 RE	F	0	20 RE	F	0	20 RE	F	0.	20 RE	F	0.	20 RE	F	T124		1.95	2.10	2.25	1.95	2.10	2.25	ND
b	0.25	0.30	0.35	0.25	0.30	0.35	0.20	0.25	0.30	0.18	0.23	0.30	0.15	0.20	0.25	T164		1.95	2.10	2.25	1.95	2.10	2.25	ND
D	3,90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	T164		1.95	2.10	2.25	1.95	2.10	2.25	YES
Ε	3.90		4.10	3.90	4.00	4.10		4.00	4.10	3.90	4.00	4.10	3.90	4.00	4.10	T164		1.95	2.10	2.25	1.95	2.10	2.25	NO
6	_	0.80	C.	_	65 BS		_	.50 BS	C.	_	.50 BS	_	_	1.40 BS		T204		1.95	2.10	2.25	1.95	2.10	2.25	NO
k	0.25	-	-	0.25	-	-	0.25	-	-	0.25	-		0.25	-	-	T204		1.95	2.10	2.25	1.95	2.10	2.25	YES
L	0.45		0.65	0.45	0.55	0.65	0.45	0.55	0.65	0.30	0.40	0.50	0.30	0.40	0.50	T204		1.95	2.10	2.25	1.95	2.10	2.25	NO.
N	-	12		-	16		_	20		-	24		<u> </u>	28	_	T24-		2.45	2.60	2.63	2.45	2.60	2.63	ND
ND ND	-	3		$\vdash$	4		_	5		$\vdash$	6		$\vdash$	7	-	T24-		1.95	2.10	2.25	1.95	2.10	2.25	YES
NE Jedec Var.	-	yGGB		$\vdash$	4 VGGC	_	Η.	5 /GGD-1	_	Η.	6 WGGD-	.0	$\vdash$	7 WGGE	-	T24-		2.45	2.60	2.63	2.45	2.60	2.63	YES
/ar.		wuus			WUUL			ייים מיטיייייייייייייייייייייייייייייייי			-עטטש	·c		WUUL		1124	4-4	2.45	2.60	2.63	2.45	2.60	2.53	NU
2.	DIMENS ALL DI	SIONING MENSION	NS ARE	IN M	LUMETE	ERS. A										T28	4-1	2.50	2.60	2.70	2.50	2.60	2.70	NO
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1. 2. 3. 4. 5. 6. 7. 16. 9. M	DIMENS ALL DIM N IS TO THE TE JESD 9 THE ZO DIMENS FROM ND ANI DEPOPE COPLAN DRAWIN MARKING COPLAN	MENSION HE TOT CRIMINAL 15—1 SI DNE INC SION B TERMIN D NE F ULATION NARITY NG CON C IS FC ARITY S	NS ARE (AL NUI PP-012 DICATED APPLIE AL TIP. REFER N IS PO APPLIE IFORMS OR PAC SHALL I	E IN MI MBER ( DENTIFIE 2. DETA 2. THE 2. TO I TO THE 2. TO I TO JE KAGE ( NOT EX	LUMETE OF TERM OR AND METALLI ON NUMB ORIENTA CCEED C	ERS. AMMINALS TERMINALS TERMINAL #1 ZED TE ER OF SYMME POSED 0220, TION F 0,08mm	NAL NI NAL MI IDENTI TRIMINAL TERMII TRICAL HEAT EXCEP	ARE IN IMBERII IDENTII FIER M AND NALS OF FASHK SINK S FFOR	NG COI FIER AI AY BE IS MEA IN EAC ON.	EES,  NMENTIC RE OPTI EITHER ASURED H D AM	IONAL, R A MO BETWE	BUT M DLD OR EEN O.: SIDE RE	UST BE MARKE 25 mm SPECTI	E LOCAT ED FEA I AND IVELY.	TURE. 0.30 m	HIN								
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